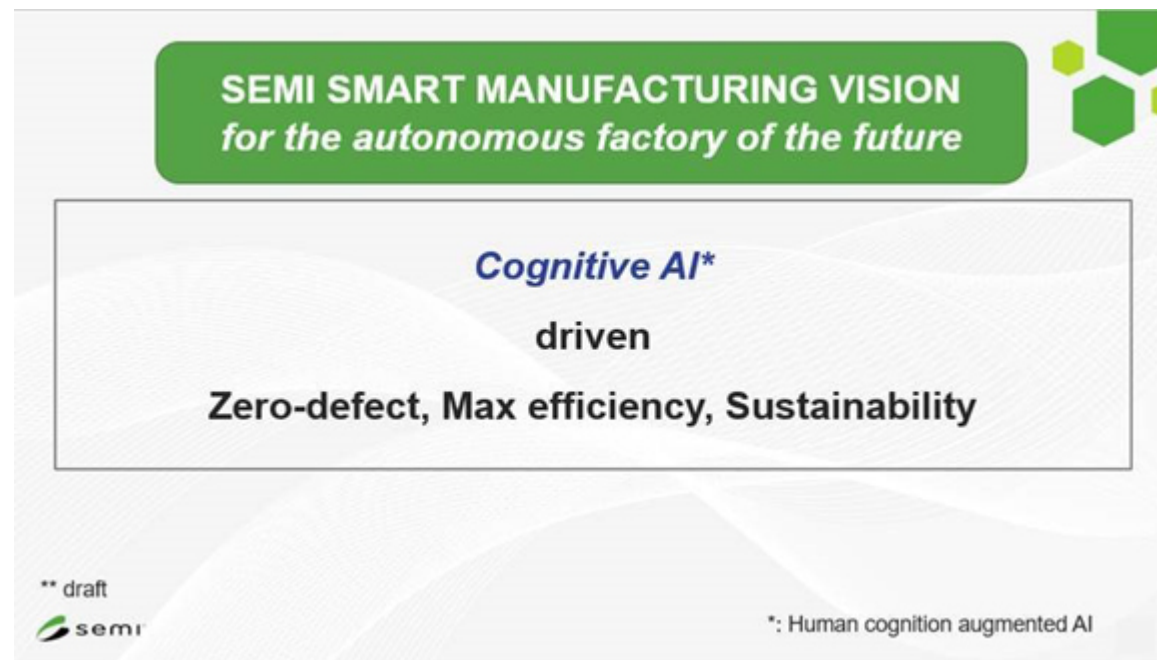




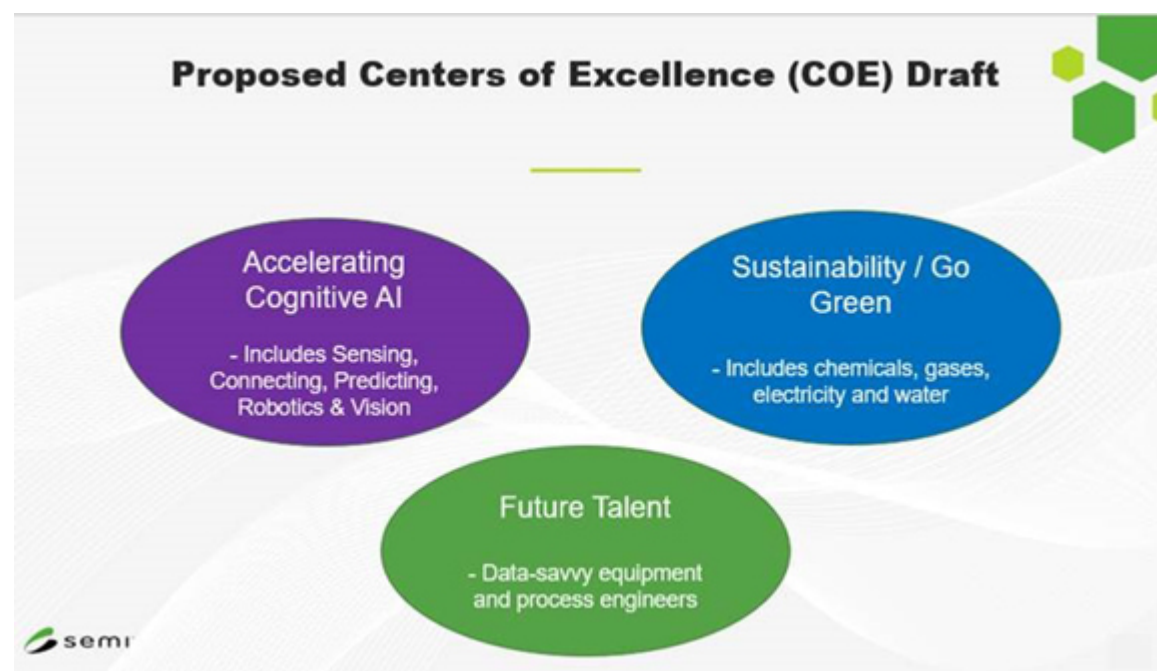
LETTER FROM THE CHAIR

We have recently taken an important step towards making our SEMI Smart Manufacturing initiative more *global*! We formed a **SEMI Smart Manufacturing Global Executive Committee (GEC)** comprising the chairs and vice-chairs of the 7 SEMI regions (Americas, Europe, China, Taiwan, SE Asia, Japan, Korea) and SEMI leaders. Our GEC session got launched with the opening address by Ajit Manocha (SEMI president & CEO) and was received with spontaneous enthusiasm from leaders across all regions.

Following is our draft vision that was presented and agreed upon by the GEC. It is a bold vision towards an **AI-driven autonomous future factory**, yet explicitly augments AI with the elements of **human cognition**. It also brings the critical results-orientation (zero-defect, max efficiency & productivity, sustainability). Tom Salmon and I also listed the key roadmap attributes that require transformation between today and 2030. I will share those broad tenets in a future article.



To achieve this vision, we formed **3 Centers of Excellence (COE): Accelerating Cognitive AI, Sustainability/Go Green and Future Talent**. Note that these are still a draft, and we welcome your valued inputs. Each SEMI region will participate in one or more of these COEs and help propel the direction.



In addition to this strategic intent, GEC will also have a tactical focus by supporting each other's key activities. For example, our SEMI 2022 Global Smart Manufacturing Conference (GSMC) will have involvement and sessions from each region. John Behnke (Inficon/FPS, and chair of GSMC) is coordinating this effort.

James Lin (United Microelectronics Corp., and vice-chair of SEMI Smart Manufacturing GEC) and I are looking forward to your strong participation in these COEs to help build the industry momentum together and achieve our bold vision!

Thanks,

Bobby Mitra
(Texas Instruments, and chair of SEMI Smart Manufacturing GEC)

FEATURED ARTICLES



Smart Manufacturing: Experts Weigh in on Talent Shortage and Solutions

Chip industry leaders and government officials are exploring fixes involving **industry investments, training infrastructure, government policies** and more investment as academia casts about for collaboration opportunities and ways to strengthen and scale skills development.



SEMI Taiwan Sets Out to Help Secure Chip Manufacturing Supply Chain with Publication of First Fab Equipment Cybersecurity Specification

In a key step to secure semiconductor manufacturing data traversing the supply chain, SEMI in mid-January published SEMI E187, a **specification designed to help protect semiconductor manufacturing data**.



SEMI Applauds Findings on Cybersecurity Hardware Adoption in Europe | SEMI

The findings mark the conclusion of a joint industry project on cybersecurity led by Coventry University's Centre for Future Transport and Cities (CFTC) Systems Security Group (SSG) to examine drivers of computer hardware security adoption among businesses and consumers. **Read the press release to access the final report.**

REGIONAL CHAPTER NEWS

Taiwan

SEMI Taiwan Smart Manufacturing Committee Highlights

- 2022 focus: Digital Transformation in Smart Manufacturing Technology Roadmap

SEMI Smart Manufacturing Global Executive Committee Highlights

- James Lin, Deputy Division Director, UMC newly joined as the vice-chair
- 2022 focus: Share and identify the scope of GEC & Proposal for Focus on Platforms/Solutions within COEs

SEMI Cybersecurity Committee Highlights

- Success in SEMICON Taiwan 2021 Cybersecurity Initiative triggered high volume of companies to join the committee and SEMI
- 2022 focus: Cybersecurity Standards Adoption, Cybersecurity Posture Assessment, Awareness Promotion

SEMI E187 Specification for Cybersecurity of Fab Equipment

- Publication of the first cybersecurity requirement baseline to secure semiconductor fab equipment by design and to support security protection in operation and maintenance – increasing demand with nearly 30 purchases within one month
- 2022 Focus: Cybersecurity (E187) training and certification

China

- Established Advanced Backend Factory Integration Task Force (ABFI TF) to explore, evaluate and develop a set of equipment automation standards for backend equipment. Leaders include Amkor Shanghai, TFME and Kxware.

Ready to join? Contact the [SEMI Smart Manufacturing Chapter Staff](#).

UPCOMING EVENTS



AI/ML ON EDGE DEVICES MASTER CLASS | MILPITAS, CA | APRIL 28, 2022

Earn CEUs and IEEE PDHs from this hands-on SEMI MSIG AI/ML on Edge Devices Master Class & Lab. A team of instructors from STMicroelectronics will explain and demonstrate how AI/ML logic can be implemented on edge devices such as smart sensors. Attendees will build and operate their own edge device with AlgoBuilder tools in 2 lab sections of the course. This course is designed for applications engineers wanting to learn how to add sensors to an existing or new product.



SMART AND SUSTAINABLE MANUFACTURING JOURNEY AT SEMICON SOUTHEAST ASIA | JUNE 21-23, 2022

Join us for an immersive experience to accelerate the adoption of smart manufacturing technologies and sustainable practices. I4.0 Roadmap, Intelligent Manufacturing Floor, Digital Reality, Sustainable Manufacturing and Light-out Factory will be in the spotlight. This will be a platform for selected members and industry partners to showcase their technology and solutions.

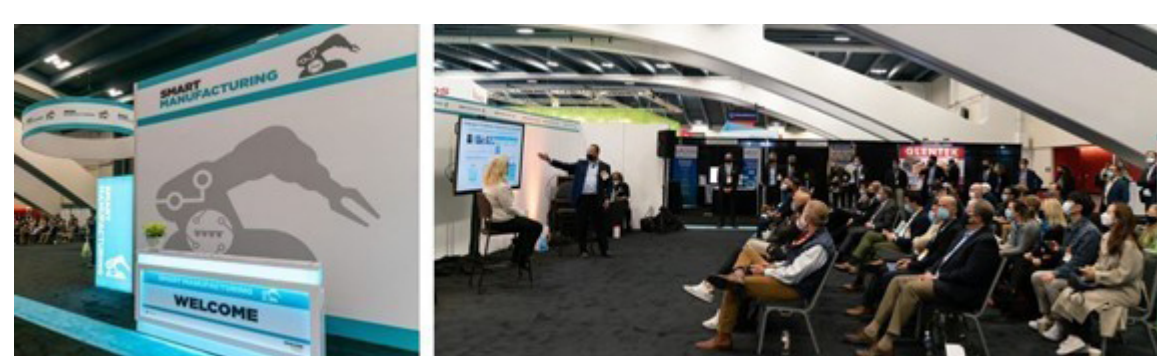


SMART MANUFACTURING PAVILLION AT SEMICON WEST | JULY 12-14, 2022

This Pavilion Program is an attendee favorite where major semiconductor makers and their suppliers present their latest capabilities incorporating digital twins, automation, predictive algorithms and more. Don't miss this opportunity to position yourself as a thought leader and share your latest advancements in Smart Manufacturing.

☞ [Submit your abstract today!](#)

☞ Sponsor or take advantage of turn-key exhibit package. Contact: Eric Rude erude@semi.org or Shane Poblete poblete@semi.org



SMART MANUFACTURING EXPO, TAIPEI, TAIWAN | SEPTEMBER 14-16, 2022

This expo will be the largest in scale in its own history, bringing together smart manufacturing solution providers across the high-tech manufacturing industry, system integrators, software and hardware vendors, and smart manufacturing demand-side players. Siemens, TSMC, ASE and 5G solution providers will reveal their forward-looking solutions in the exhibition. Mirle, Mindman, SAA will display their advanced automation equipment. TXone and ITRI will partner with SEMI Taiwan to enhance the awareness of semiconductor cybersecurity.

Questions? [Start here.](#)

Do you have a colleague who would be interested in receiving future newsletters? [Please share!](#)

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